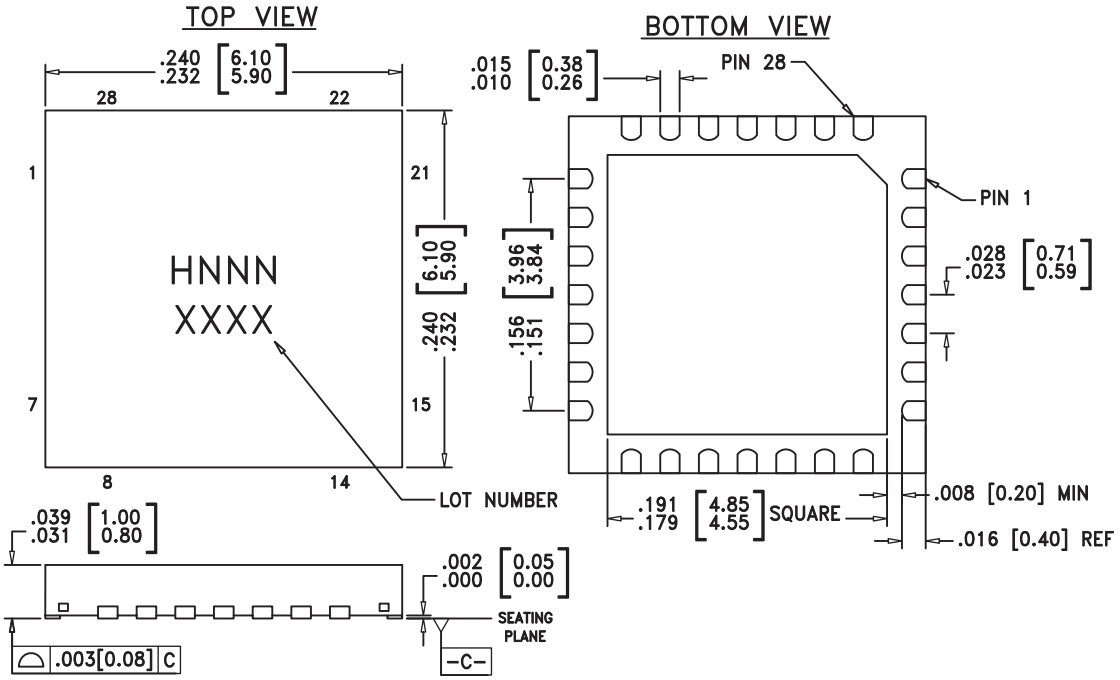
LP6 (E) – 6 x 6 mm QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE

LP6 (E) Package Outline Drawing



NOTES:

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. PAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
LP6	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	HNNN XXXX
LP6E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	HNNN XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX
[4] 3-Digit part number NNN

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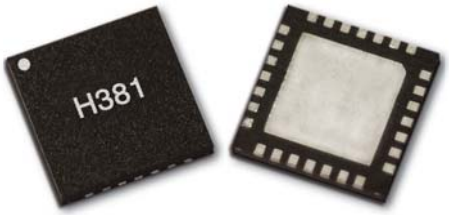
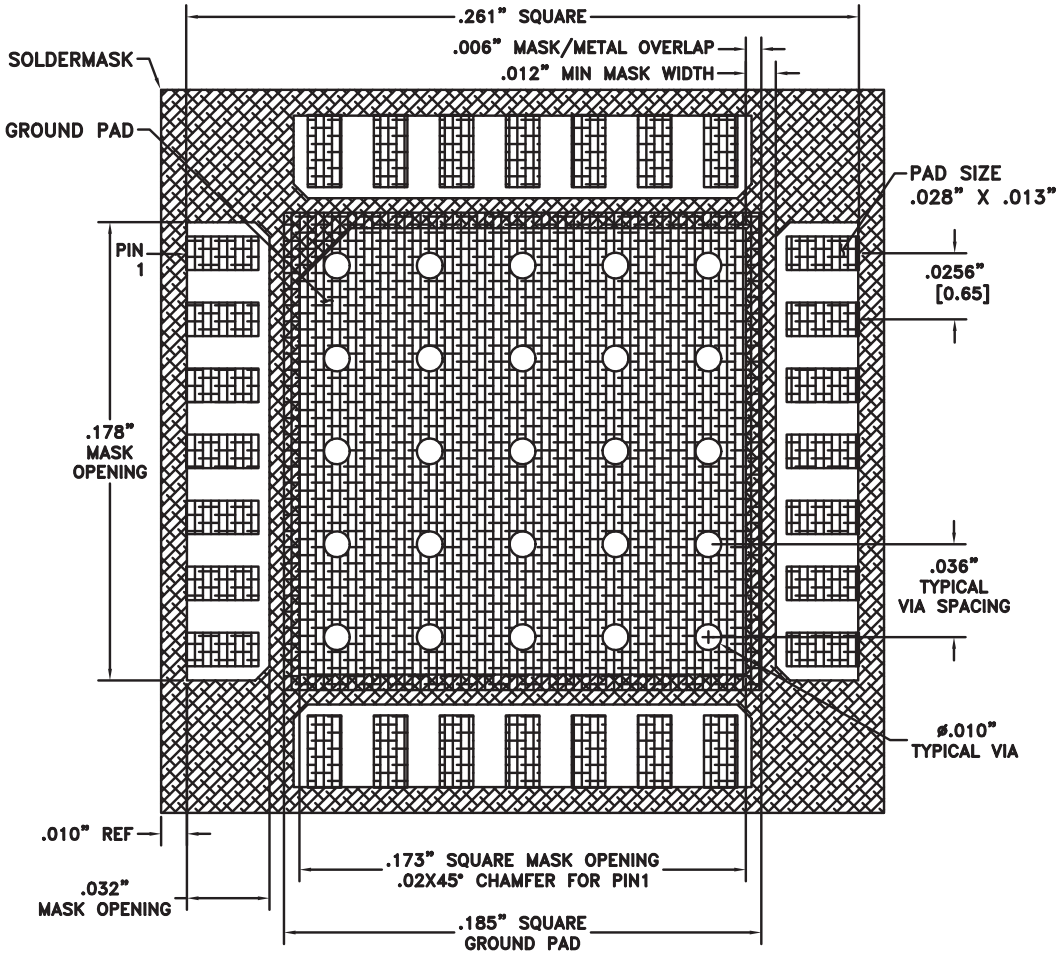
Suggested LP6 (E) PCB Land Pattern





NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.
3. SOLDERMASK ON FAR SIDE SHOULD TENT OR PLUG VIA HOLES.